



Abstract

The invention relates to processes for producing copy protection for an integrated circuit.

To avoid unauthorized copying of an integrated circuit, it is an object of the invention to provide an effective and reliable copy protection.

The invention proposes a process comprising the steps of providing a substrate (1) which has semiconductor structures (2) on at least a first side (1a) of the substrate (1), providing a material (23) for coating the substrate (1), coating the substrate (1) with a copy-protect layer (4).

It has proven particularly advantageous for the copy-protect layer (4) to be produced by applying a silicate glass by evaporation coating, since this means that an etching process which dissolves the copy-protect layer also attacks the substrate (1), in such a manner that the semiconductor structures (2) are at least partially destroyed.